

4~12wafers Fully automatic wafer etching machine

Model: SA-WEM-48LS

SA-WEM-48LS features a specially designed rotating mechanism for steady immersion processing. It delivers highly uniform etching results and adopts circulating filtration to reuse chemical liquids. With intelligent temperature control and gas regulating functions, it works efficiently. It supports data interconnection with management systems and has comprehensive protection designs to safeguard wafers during operation.



Feature

- Immersion Etching Cleaning
- Special Rotary Basket Mechanism
- Adjustable Nitrogen Bubbling Rate
- Support MES system
- Inline Heating, Cooling and Constant Temperature

Application

- Wafer Front-End Cleaning
- Photolithography Cleaning
- Etch Post-Cleaning
- Thin Film Cleaning
- Back-End Packaging

Specifications:

Parameter	Descriptions
Wafer Size	4"~12"
Ness Increment	$\delta TTV \leq 1.5\mu m$
Cleaning Capacity	6": 75pieces/time 8"/12": 50pieces/time